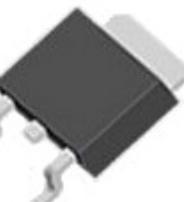
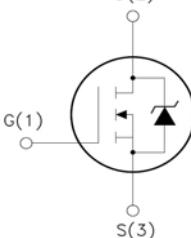


CTKD60N04 40V N-Channel MOSFET Features: <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances. <input type="checkbox"/> Excellent Switching Characteristics. <input type="checkbox"/> Extended Safe Operating Area. <input type="checkbox"/> Unrivalled Gate Charge :Qg= 29nC (Typ.). <input type="checkbox"/> BVDSS=40V, ID=60A <input type="checkbox"/> RDS(on) : 0.008Ω (Max) @VG=10V <input type="checkbox"/> 100% Avalanche Tested 	 TO-252  1. Gate (G) 2. Drain (D) 3. Source (S)
--	--

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	40	V
I_D	Drain Current	$T_c=25^\circ\text{C}$	60
		$T_c=100^\circ\text{C}$	42
$V_{GS(TH)}$	Gate Threshold Voltage	± 25	V
E_{AS}	Single Pulse Avalanche Energy (note5)	400	mJ
I_{AR}	Avalanche Current (note2)	60	A
P_D	Power Dissipation ($T_a=25^\circ\text{C}$)	65	W
T_j	Junction Temperature(Max)	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+175	
T_L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	2.3	$^\circ\text{C}/\text{W}$

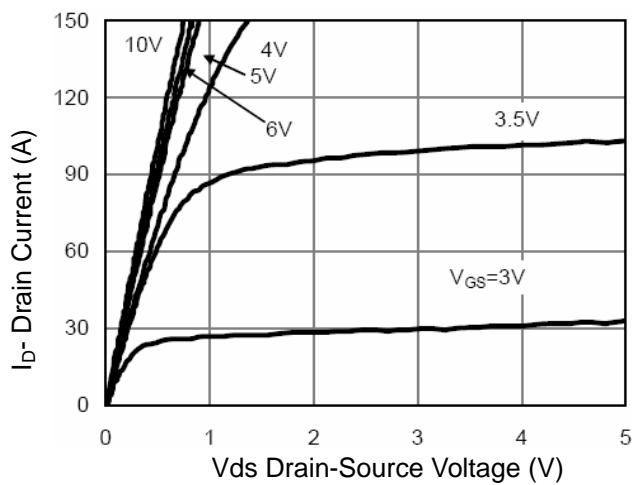
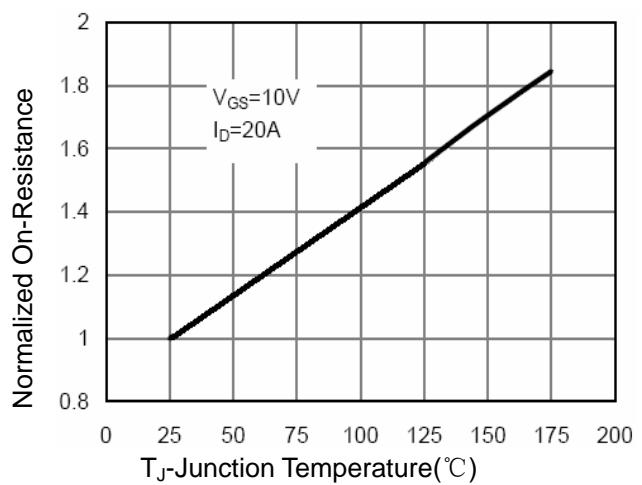
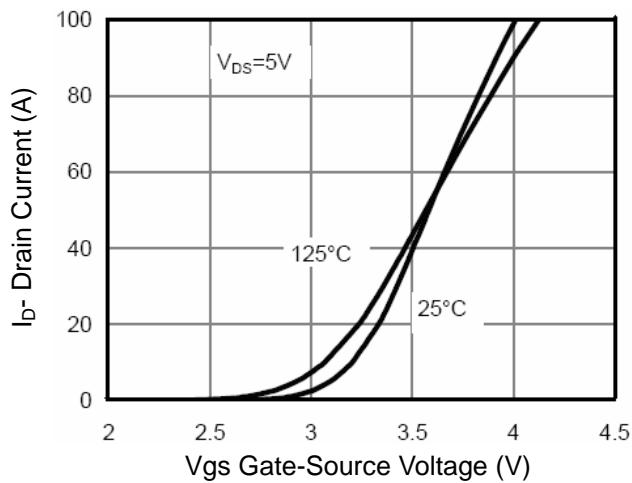
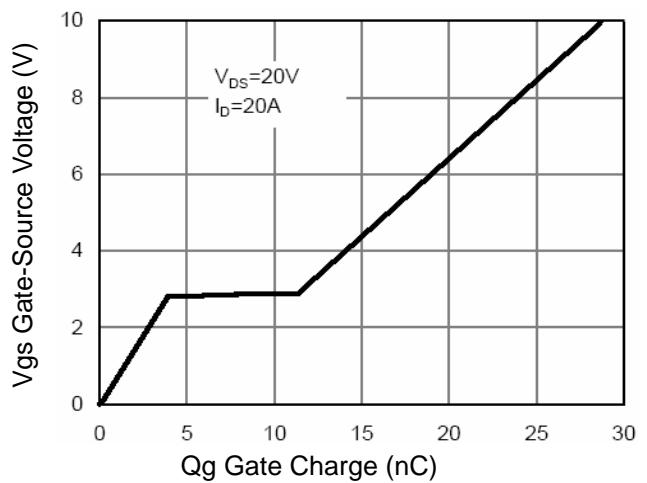
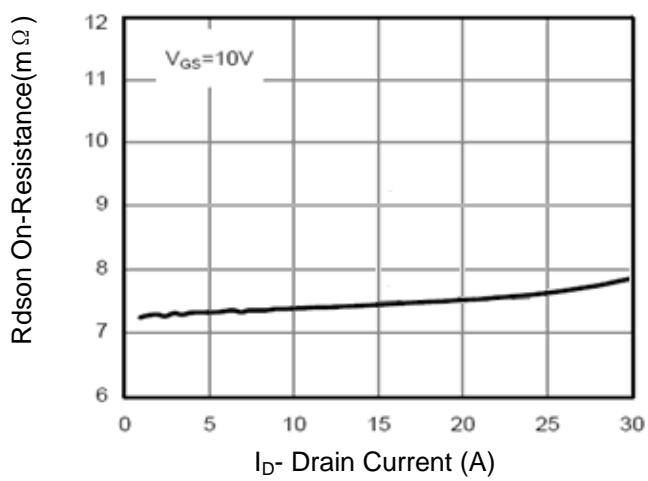
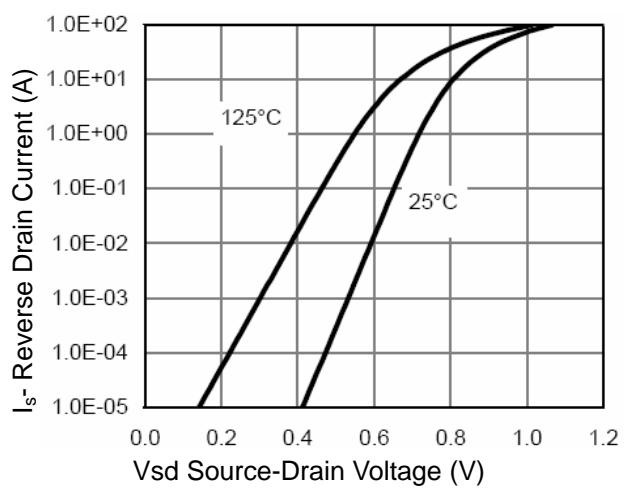
Electrical Characteristics ($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	V_{DSS}	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40	45	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	-	-	± 100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.2	1.6	2.5	V
Drain-Source On-State Resistance	$R_{DS(\text{ON})}$	$V_{GS}=10\text{V}, I_D=20\text{A}$	-	7.3	8	$\text{m } \Omega$
Forward Transconductance	g_{FS}	$V_{DS}=10\text{V}, I_D=20\text{A}$	15	-	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=20\text{V}, V_{GS}=0\text{V}, F=1.0\text{MHz}$	-	1800	-	PF
Output Capacitance	C_{oss}		-	280	-	PF
Reverse Transfer Capacitance	C_{rss}		-	190	-	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=20\text{V}, I_D=2\text{A}, R_L=1\Omega$ $V_{GS}=10\text{V}, R_G=3\Omega$	-	6.4	-	nS
Turn-on Rise Time	t_r		-	17.2	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	29.6	-	nS
Turn-Off Fall Time	t_f		-	16.8	-	nS
Total Gate Charge	Q_g	$V_{DS}=20\text{V}, I_D=20\text{A}, V_{GS}=10\text{V}$	-	29	-	nC
Gate-Source Charge	Q_{gs}		-	4.5	-	nC
Gate-Drain Charge	Q_{gd}		-	6.4	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{GS}=0\text{V}, I_S=10\text{A}$	-		1.2	V
Diode Forward Current ^(Note 2)	I_S		-	-	60	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, IF = 20\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ ^(Note 3)	-	29	-	nS
Reverse Recovery Charge	Q_{rr}		-	26	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

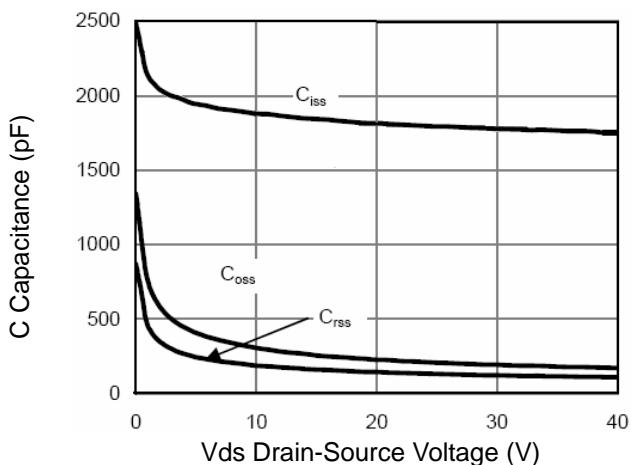
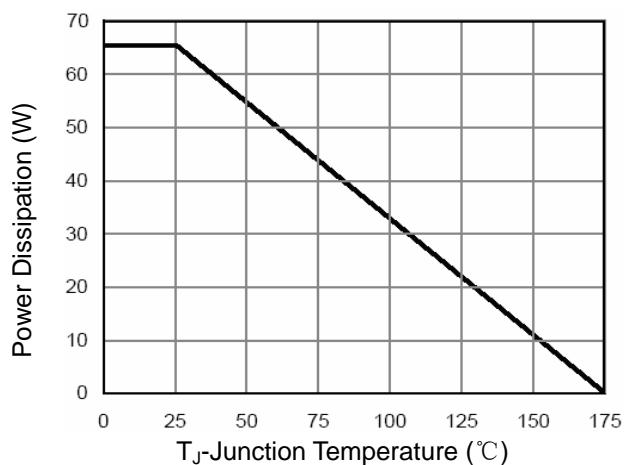
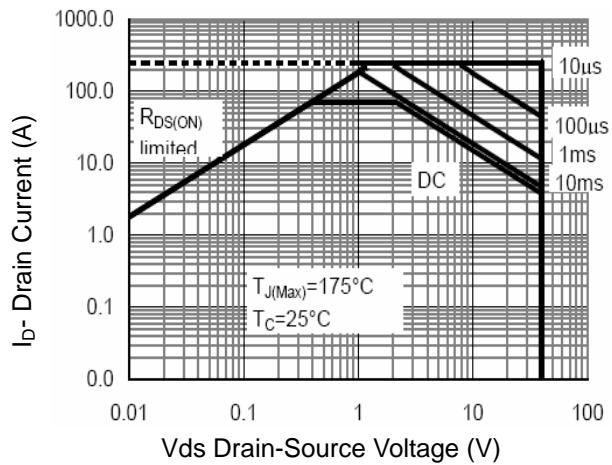
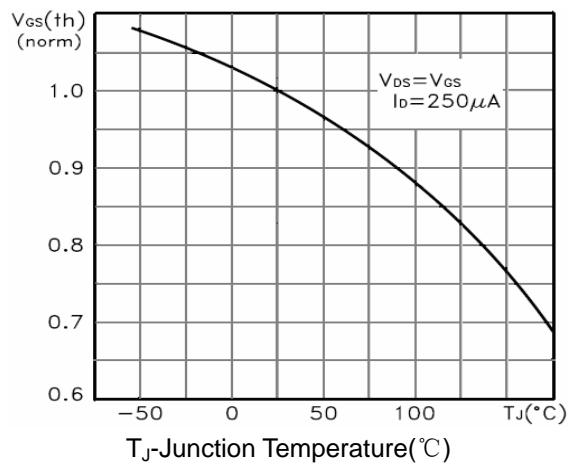
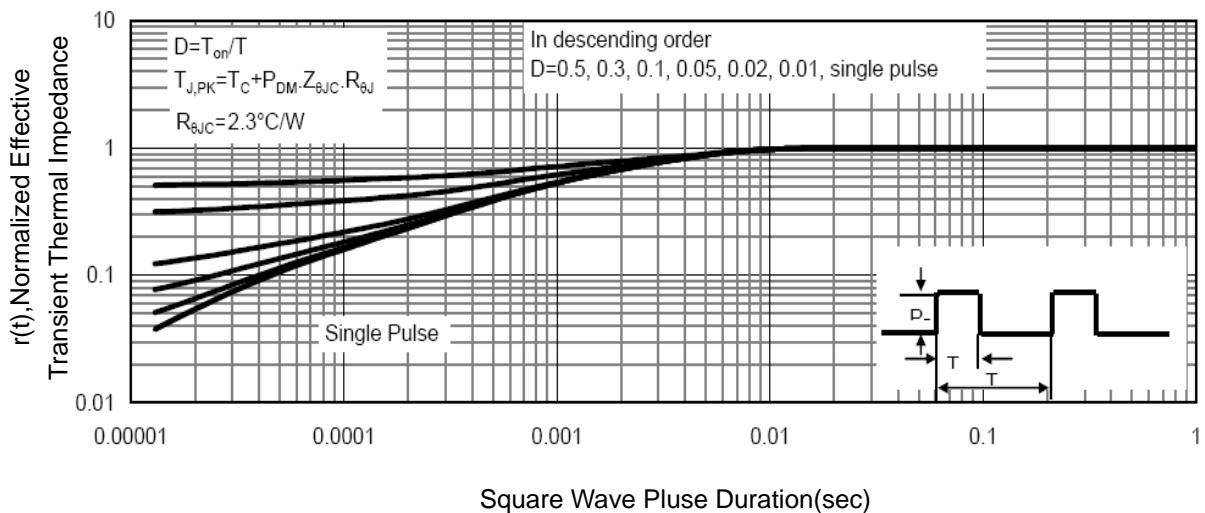
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. E_{AS} condition : $T_j=25^\circ\text{C}, V_{DD}=20\text{V}, V_G=10\text{V}, L=1\text{mH}, R_g=25\Omega$,

Typical Characteristics

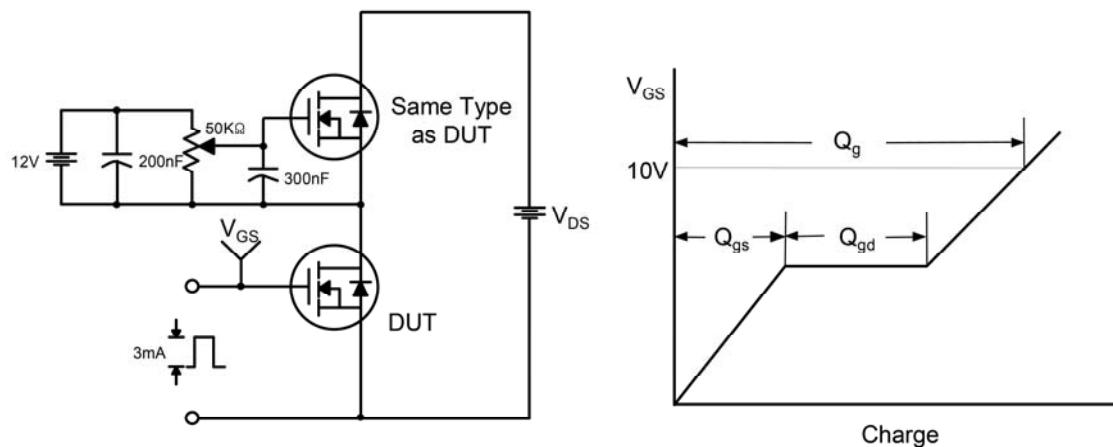
**Figure 1 Output Characteristics****Figure 4 Rdson-JunctionTemperature****Figure 2 Transfer Characteristics****Figure 5 Gate Charge****Figure 3 Rdson- Drain Current****Figure 6 Source- Drain Diode Forward**

Typical Characteristics (Continued)

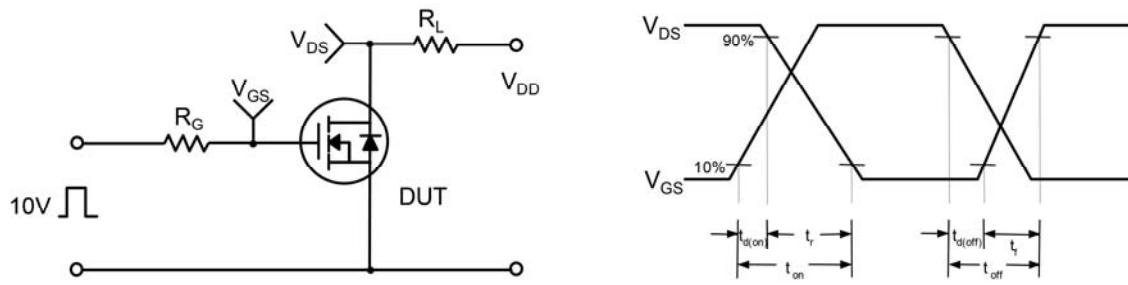
40V N-Channel MOSFET


Figure 7 Capacitance vs Vds

Figure 9 Power De-rating

Figure 8 Safe Operation Area

Figure 10 $V_{GS(th)}$ vs Junction Temperature

Figure 11 Normalized Maximum Transient Thermal Impedance

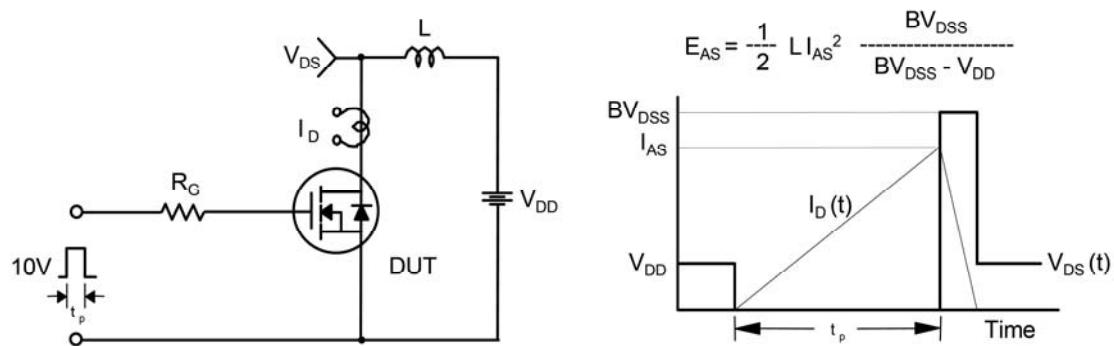
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

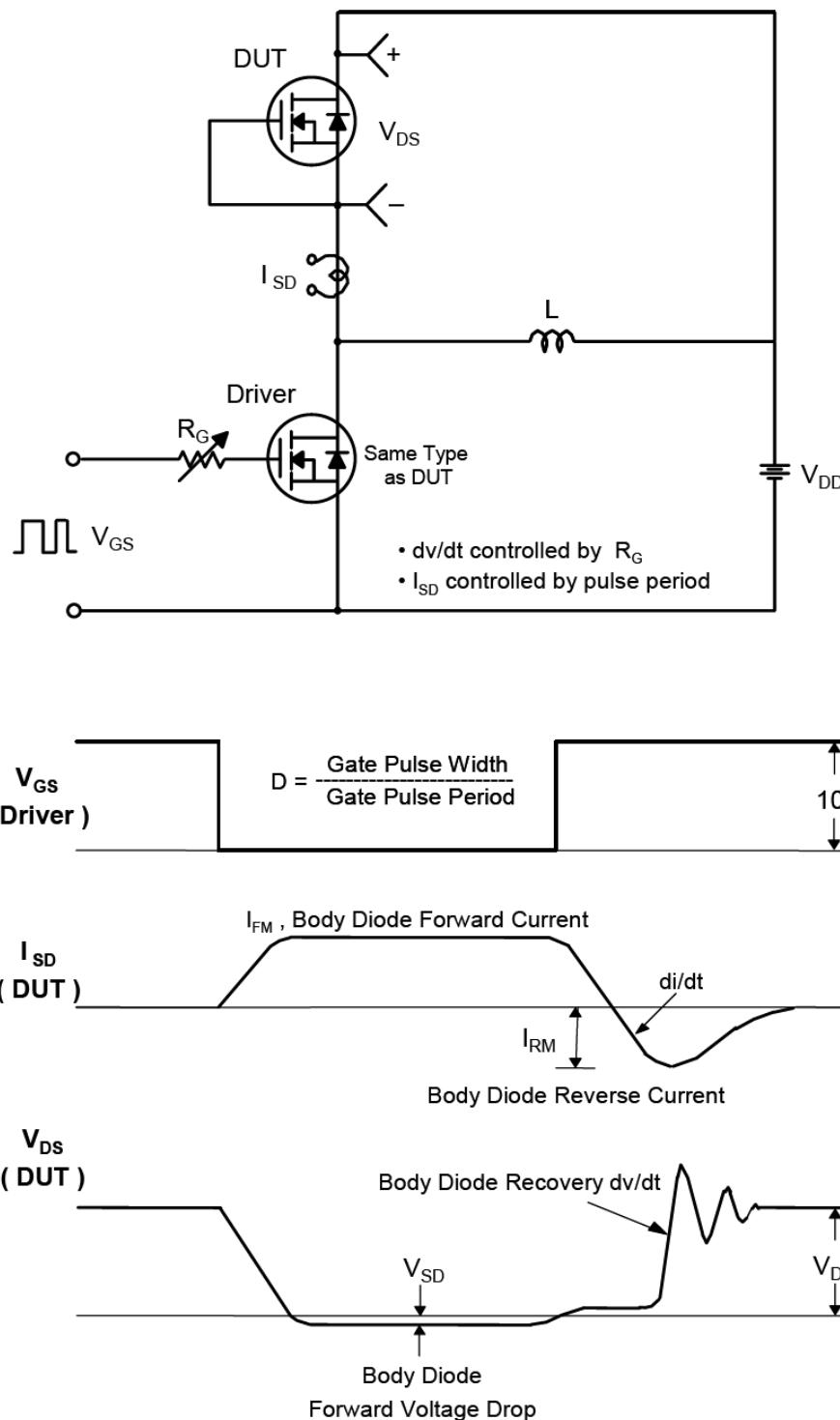


Unclamped Inductive Switching Test Circuit & Waveforms



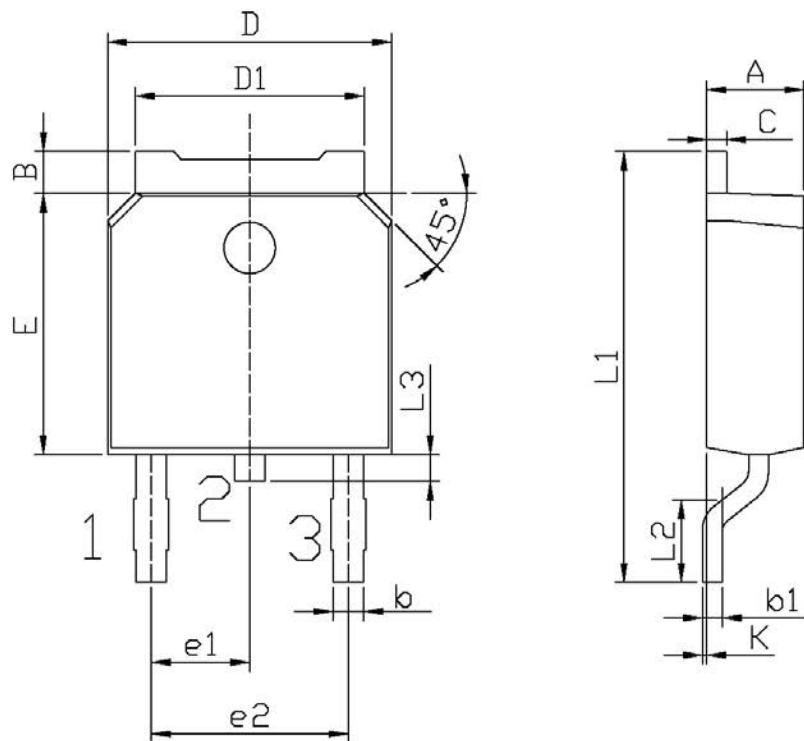
Peak Diode Recovery dv/dt Test Circuit & Waveform

40V N-Channel MOSFET



Package Dimension

TO-252 Unit: mm



单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.70	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.85	10.35
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.20	5.40	K	0.00	0.10